

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/25/2022

Details for "THS4001ID"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
THS4001ID	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 8	3.91x4.9x1.58	84.6

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.00131	13	0.000001	0
Precious Metals	Gold	7440-57-5	0.07635	99.997381	999974	0.090226	902
Precious Metals	Silver	7440-22-4	0.000001	0.00131	13	0.000001	0
Sub-Total			0.076352	100	1000000	0.090228	902
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.130426	80.000245	800002	0.154129	1541
Thermoplastics	Epoxy	85954-11-6	0.032606	19.999755	199998	0.038532	385
Sub-Total			0.163032	100	1000000	0.192661	1927
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	28.663182	286632
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.706207	7062
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.008828	88
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.008828	88
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.008828	88
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.029425	294
Sub-Total			24.9	100	1000000	29.425297	294253
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.41984	4198
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003442	34
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.018097	181
Sub-Total			0.3735	100	1000000	0.441379	4414
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	51.546175	87.999998	880000	60.914118	609141
Other Plastics and Rubber	Carbon Black	1333-86-4	0.175726	0.300001	3000	0.207662	2077
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.322164	0.550001	5500	0.380714	3807
Thermoplastics	Epoxy	85954-11-6	6.531135	11.15	111500	7.718096	77181
Sub-Total			58.5752	100	1000000	69.220589	692206
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.532981	100	1000000	0.629844	6298
Sub-Total			0.532981	100	1000000	0.629844	6298
Total			84.621065			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.